

PCN Number:	20251118000.2B		PCN Date:	February 12, 2026	
Title:	Qualify UTL as an additional Assembly/Test site for select devices				
Customer Contact:	Change Management team		Dept:	Quality Services	
Proposed 1st Ship Date:	May 20, 2026		Sample requests accepted until:	January 20, 2026*	
*Sample requests received after January will not be supported.					
Change Type:					
☒	Assembly Site	☐	Design	☐	Wafer Bump Material
☐	Assembly Process	☐	Data Sheet	☐	Wafer Bump Process
☒	Assembly Materials	☐	Part number change	☐	Wafer Fab Site
☐	Mechanical Specification	☒	Test Site	☐	Wafer Fab Material
☒	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Process
PCN Details					
Description of Change:					
Texas Instruments is pleased to announce the qualification UTL (Subcon) as an additional Assembly/Test site for the list of devices shown below. Material differences between sites are as follows.					
Purpose of this correction to revision B is to update ZVEI ID originally stated in the PCN Letter					
Assembly Site					
	Current Site	Additional Site			
Assembly Site	ATXSZ	UTL			
LEAD Frame	SID#1107151101	SID#FU0148			
Mount Compound	Sid#1400336111	SID#PZ0084			
Qual details are provided in the Qual Data Section. Test coverage, insertions, conditions will remain consistent with current testing.					
Reason for Change:					
Continuity of supply.					
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):					
None.					
Impact on Environmental Ratings					
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.					
RoHS	REACH	Green Status	IEC 62474		
☒ No Change	☒ No Change	☒ No Change	☒ No Change		
Changes to product identification resulting from this PCN:					

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
ATXSZ	ASN	CHN	Suzhou
UTL	UTL1/2/3	TH	Bangkok

Sample product shipping label (not actual product label)

**TEXAS
INSTRUMENTS**
MADE IN: Malaysia
2DC: 2d:
MSL 2 / 260C / 1 YEAR
MSL 1 / 235C / UNLIM
SEAL DT
03/29/04
OPT:
ITEM: 39
LBL: 5A (L)T0:1750


G4



(1P) **SN74LS07NSR**
(Q) **2000** (D) **0336**
(31T) LOT: 3959047MLA
(4W) TKY (1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CS0: SHE (21L) CC0: USA
(22L) AS0: MLA (23L) ACO: MYS

Product Affected:

1P1G125QDRYRQ1	1P1G126QDRYRQ1	1P2GU04QDRYRQ1
SN74LVC1G07QDRYRQ1	SN74LVC1G08QDRYRQ1	SN74LVC1G14QDRYRQ1
SN74LVC1G32QDRYRQ1	TXU0101QDRYRQ1	
SN74AXC1T45QDRYRQ1	SN74LVC1G17QDRYRQ1	

Automotive Qualification Summary (As per AEC-Q100 Rev. J and JEDEC Guidelines)

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: SN74LVC1G08QDRYRQ1	QBS Process Reference: SN3257QDYYRQ1	QBS Package Reference: TMP451A QDQFRQ1
Test Group A - Accelerated Environment Stress Tests										
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	MSL1 260C	-	3/0/0	3/0/0	3/0/0
HAST	A2	JEDEC JESD22-A110	3	77	Biased HAST	130C/85%RH	96 Hours	3/231/0	3/231/0	3/231/0
AC/UHAST	A3	JEDEC JESD22-A102/JEDEC JESD22-A118	3	77	Autoclave	121C/15psig	96 Hours	-	3/231/0	3/231/0
AC/UHAST	A3	JEDEC JESD22-A102/JEDEC JESD22-A118	3	77	Unbiased HAST	130C/85%RH	96 Hours	3/231/0	-	-
TC	A4	JEDEC JESD22-A104 and Appendix 3	3	77	Temperature Cycle	-65C/150C	500 Cycles	3/231/0	3/231/0	3/231/0
TC-BP	A4	MIL-STD883 Method 2011	1	5	Post Temp Cycle Bond Pull	-	-	1/5/0	-	1/5/0
HTSL	A6	JEDEC JESD22-A103	1	45	High Temperature Storage Life	150C	1000 Hours	1/45/0	3/135/0	-
HTSL	A6	JEDEC JESD22-A103	1	45	High Temperature Storage Life	175C	500 Hours	-	-	1/45/0
Test Group B - Accelerated Lifetime Simulation Tests										

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: SN74LVC1G08QDRYRQ1	QBS Process Reference: SN3257QDYYRQ1	QBS Package Reference: TMP451AQDQFRQ1
HTOL	B1	JEDEC JESD22-A108	3	77	Life Test	150C	300 Hours	-	3/231/0	-
HTOL	B1	JEDEC JESD22-A108	3	77	Life Test	150C	408 Hours	-	-	3/231/0
ELFR	B2	AEC Q100-008	3	800	Early Life Failure Rate	150C	24 Hours	-	3/2400/0	3/2400/0
Test Group C - Package Assembly Integrity Tests										
WBS	C1	AEC Q100-001	1	30	Wire Bond Shear	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	1/30/0	3/90/0	3/90/0
WBP	C2	MIL-STD883 Method 2011	1	30	Wire Bond Pull	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	1/30/0	3/90/0	3/90/0
SD	C3	JEDEC J-STD-002	1	15	PB Solderability	>95% Lead Coverage	-	-	1/15/0	-
SD	C3	JEDEC J-STD-002	1	15	PB-Free Solderability	>95% Lead Coverage	-	-	1/15/0	-
PD	C4	JEDEC JESD22-B100 and B108	3	10	Physical Dimensions	Cpk>1.67	-	1/10/0	3/30/0	3/30/0
Test Group D - Die Fabrication Reliability Tests										
EM	D1	JESD61	-	-	Electromigration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
Tddb	D2	JESD35	-	-	Time Dependent Dielectric Breakdown	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: SN74LVC1G08QDRYRQ1	QBS Process Reference: SN3257QDYYRQ1	QBS Package Reference: TMP451AQDQFRQ1
HCI	D3	JESD60 & 28	-	-	Hot Carrier Injection	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
BTI	D4	-	-	-	Bias Temperature Instability	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
SM	D5	-	-	-	Stress Migration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
Test Group E - Electrical Verification Tests										
ESD	E2	AEC Q100-002	1	3	ESD HBM	-	2000 Volts	1/3/0	1/3/0	1/3/0
ESD	E3	AEC Q100-011	1	3	ESD CDM	-	1500 Volts	-	1/3/0	-
ESD	E3	AEC Q100-011	1	3	ESD CDM	-	500 Volts	1/3/0	-	1/3/0
LU	E4	AEC Q100-004	1	3	Latch-Up	Per AEC Q100-004	-	1/3/0	1/6/0	1/6/0
ED	E5	AEC Q100-009	3	30	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	1/30/0	3/90/0	3/90/0
Additional Tests										

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Ambient Operating Temperature by Automotive Grade Level:

- Grade 0 (or E): -40C to +150C
- Grade 1 (or Q): -40C to +125C
- Grade 2 (or T): -40C to +105C
- Grade 3 (or I) : -40C to +85C

E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):

- Room/Hot/Cold : HTOL, ED
- Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU
- Room : AC/uHAST

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2409-069

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

ZVEI ID: SEM-PA-03, SEM-PA-05, SEM-PA-07, SEM-PA-18, SEM-TF-01

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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